MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

onsemi

X4DFN2, 0.60x0.30x0.19, 0.36P
CASE 152AX
ISSUE H

DATE 01 AUG 2023

TOP VIEW

PIN 1 INDICATOR NOTE 3

SIDE VIEW

SEATING PLANE

BOTTOM VIEW
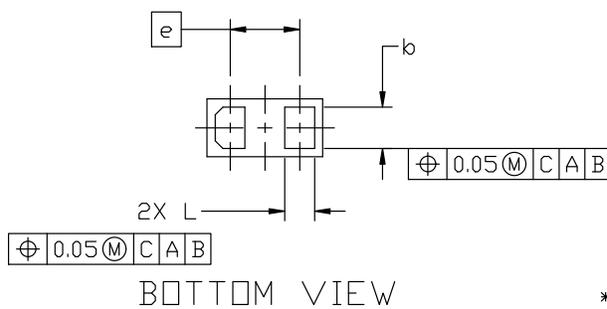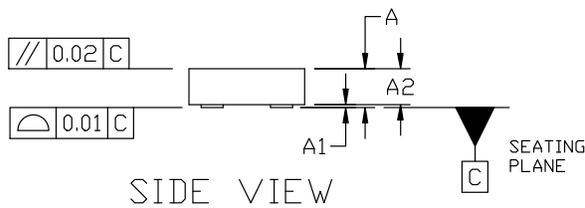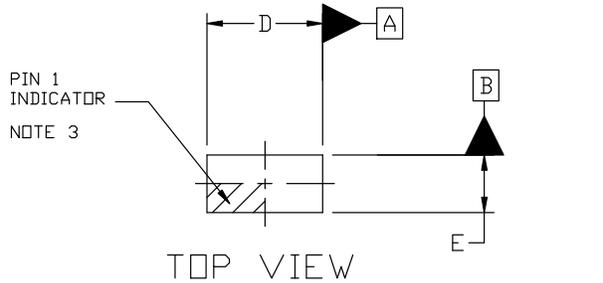
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

2. CONTROLLING DIMENSION: MILLIMETERS

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.175	0.200	0.225
A1	0.018 REF		
A2	0.180	0.190	0.200
b	0.205	0.215	0.225
D	0.575	0.600	0.625
E	0.275	0.300	0.325
e	0.36 BSC		
L	0.145	0.155	0.165

RECOMMENDED MOUNTING FOOTPRINT

0.65
2X 0.27
2X 0.26
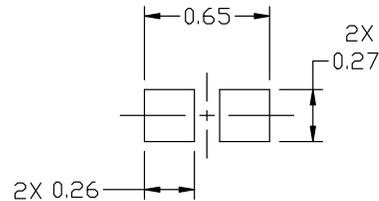
* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*
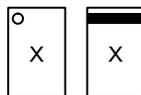
X = Specific Device Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	X4DFN2, 0.60x0.30x0.19, 0.36P		PAGE 1 OF 1